

Product / Process Change Notification



N° 2017-023-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of new lead frame material for TSLP & TSSLP packages

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **5. January 2018**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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► **Products affected:**

Sales Name	SP N°	OPN	Package
Refer to 1_cip17023A			

► **Detailed Change Information:**

Subject: Introduction of new leadframe material for TSLP & TSSLP packages

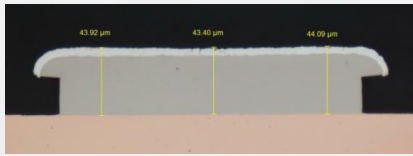
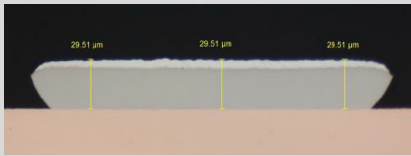
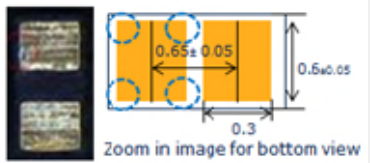
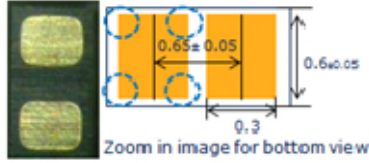
Reason: To further ensure our product supply the new leadframe material will be introduced

Description:

- Leadframe
- Leadframe bump shape

- Footprint

- Remarks

	<u>Old</u>	<u>New</u>
	NiAg / NiAu	NiPdAu/ NiPdAg
	Mushroom 	Tapered 
	 Zoom in image for bottom view	 Zoom in image for bottom view
	✓ Sharp pad radius	<ul style="list-style-type: none"> ✓ Round shape pad radius ✓ The new pad shape is due to the new leadframe design ✓ Reflow Soldering and Package dimension remain UNCHANGED. ✓ Lead pitching remain UNCHANGED

► **Product Identification:**

Internal traceability ensured via Baunumber, Lot number & date code

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► Impact of Change:

- Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No change in fit and form (except round shape pad radius)
- Products with new pad design are fully compatible on board at customers end
- Reflow Soldering and Package dimension remain **UNCHANGED**.
- Lead pitching remain **UNCHANGED**

► Attachments:

Affected product list (1_cip17023)
Final qualification report (2_cip17023)

► Time Schedule:

- | | |
|-------------------------------|---|
| ■ Final qualification report: | Available (2_cip17023) |
| ■ First samples available: | Upon request |
| ■ Intended start of delivery: | 15.02.2018 onwards, or earlier based on customer approval
Existing stock will be depleted first (FIFO) |

If you have any questions, please do not hesitate to contact your local Sales office.